Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	500			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.48		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 500 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 400 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	aracteristics				•	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 6.7 A		0.33	0.43	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 6.7 A (Note 4)		10.3		S
C _{oss} C _{rss}	Output Capacitance Reverse Transfer Capacitance	f = 1.0 MHz		245 25	320 35	pF pF
C _{oss}	· ' '	f = 1.0 MHz				•
0!4!						
	Ing Characteristics			40	90	no
t _{d(on)}	Turn-On Delay Time Turn-On Rise Time	$V_{DD} = 250 \text{ V}, I_{D} = 13.4 \text{ A},$		140	290	ns
t _r	Turn-Off Delay Time	$R_G = 25 \Omega$		100	210	ns
t _{d(off)}	Turn-Off Fall Time	(Note 4, 5)		85	180	ns ns
Q _q	Total Gate Charge	\(\ - 400\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		45	60	nC
Q _{gs}	Gate-Source Charge	$V_{DS} = 400 \text{ V}, I_D = 13.4 \text{ A},$ $V_{GS} = 10 \text{ V}$		11		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		22		nC
gu						
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				13.4	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				53.6	Α
	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 13.4 A			1.4	V
V_{SD}	Brain Course Blode I chivara Voltage					
V _{SD}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 13.4 A,		290		ns

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 8.1mH, I_{AS} = 13.4A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25°C 3. $I_{SD} \leq$ 13.4A, $di/dt \leq$ 200A/μs, $V_{DD} \leq$ BV $_{DSS}$, Starting T_{J} = 25°C 4. Pulse Test : Pulse width \leq 300 μ s, Duty cycle \leq 2% 5. Essentially independent of operating temperature

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Typical Characteristics

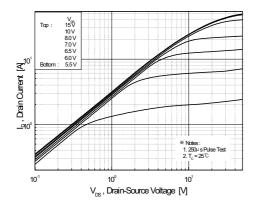


Figure 1. On-Region Characteristics

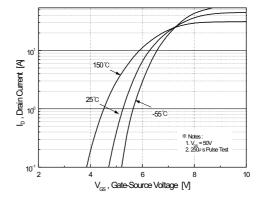


Figure 2. Transfer Characteristics

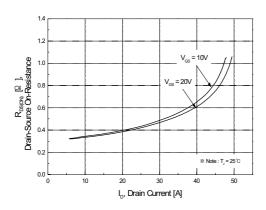


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

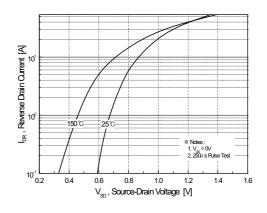


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

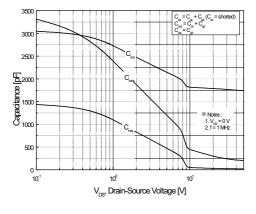


Figure 5. Capacitance Characteristics

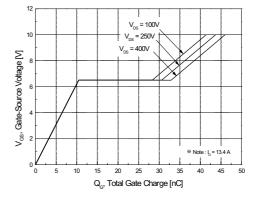
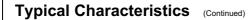
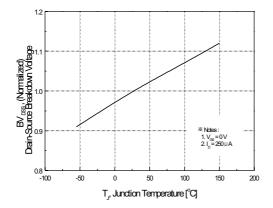


Figure 6. Gate Charge Characteristics

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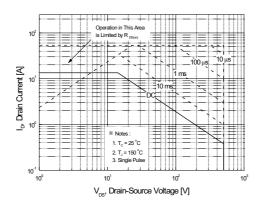




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Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



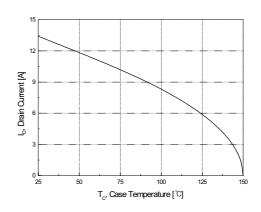


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

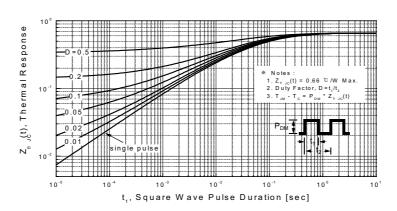
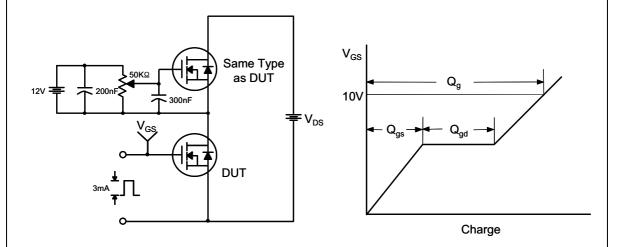


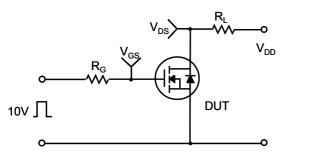
Figure 11. Transient Thermal Response Curve

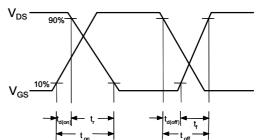
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Gate Charge Test Circuit & Waveform

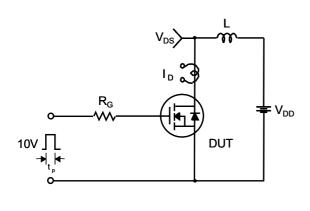


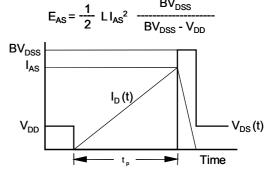
Resistive Switching Test Circuit & Waveforms



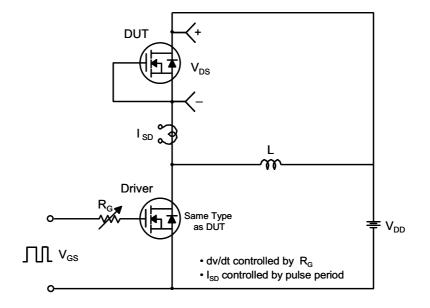


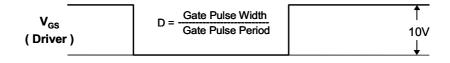
Unclamped Inductive Switching Test Circuit & Waveforms

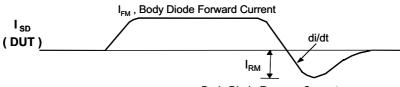




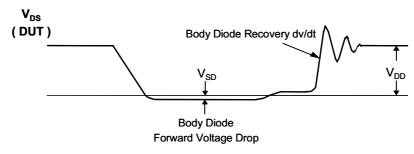
Peak Diode Recovery dv/dt Test Circuit & Waveforms



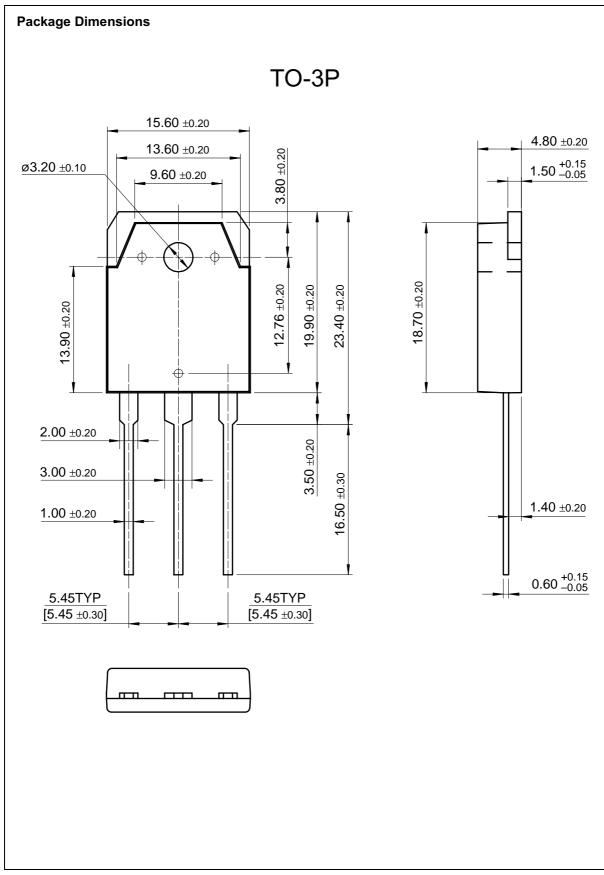




Body Diode Reverse Current



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